DATA SHEET

MCR08BT1
Thyristor logic level

Product specification

July 2001

Philips
Semiconductors

PHILIPS

Thyristor logic level MCR08BT1

GENERAL DESCRIPTION

Passivated, sensitive gate thyristor in a plastic envelope, suitable for surface mounting, intended for use in general purpose switching and phase control applications. This device is intended to be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

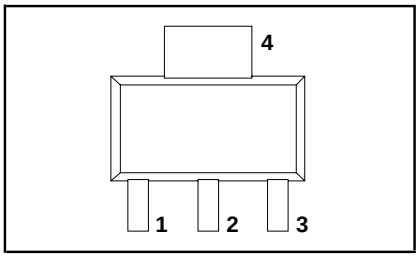
QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
V_{DRM}, V_{RRM}	Repetitive peak off-state voltages	200	V
$I_{T(AV)}$	Average on-state current	0.5	A
$I_{T(RMS)}$	RMS on-state current	0.8	A
I_{TSM}	Non-repetitive peak on-state current	9	A

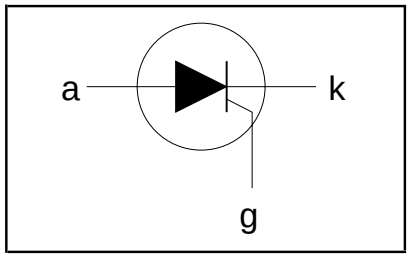
PINNING - SOT223

PIN	DESCRIPTION
1	cathode
2	anode
3	gate
tab	anode

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{DRM}, V_{RRM}	Repetitive peak off-state voltages		-	200[1]	V
$I_{T(AV)}$	Average on-state current	half sine wave; $T_{sp} \leq 112$ ˚C	-	0.5	A
$I_{T(RMS)}$	RMS on-state current	all conduction angles	-	0.8	A
I_{TSM}	Non-repetitive peak on-state current	half sine wave; $T_j = 25$ ˚C prior to surge			
		t = 10 ms	-	8	A
		t = 8.3 ms	-	9	A
I^2t	I^2t for fusing	t = 10 ms	-	0.32	A^2s
dI_T/dt	Repetitive rate of rise of on-state current after triggering	I_{TM} = 2 A; I_G = 10 mA; dI_G/dt = 100 mA/µs	-	50	A/µs
I_{GM}	Peak gate current		-	1	A
V_{GM}	Peak gate voltage		-	5	V
V_{RGM}	Peak reverse gate voltage		-	5	V
P_{GM}	Peak gate power		-	2	W
$P_{G(AV)}$	Average gate power	over any 20 ms period	-	0.1	W
T_{stg}	Storage temperature		-40	150	˚C
T_j	Operating junction temperature		-	125	˚C

1 Although not recommended, off-state voltages up to 800V may be applied without damage, but the thyristor may switch to the on-state. The rate of rise of current should not exceed 15 A/µs.

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th\ j\text{-}sp}$	Thermal resistance junction to solder point		-	-	15	K/W
$R_{th\ j\text{-}a}$	Thermal resistance junction to ambient	pcb mounted, minimum footprint	-	156	-	K/W
		pcb mounted; pad area as in fig:14	-	70	-	K/W

STATIC CHARACTERISTICS

T_j = 25 ˚C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{GT}	Gate trigger current	V_D = 12 V; I_T = 10 mA; gate open circuit	-	50	200	µA
I_L	Latching current	V_D = 12 V; I_{GT} = 0.5 mA; R_{GK} = 1 kΩ	-	2	6	mA
I_H	Holding current	V_D = 12 V; I_{GT} = 0.5 mA; R_{GK} = 1 kΩ	-	2	5	mA
V_T	On-state voltage	I_T = 2 A	-	1.35	1.5	V
V_{GT}	Gate trigger voltage	V_D = 12 V; I_T = 10 mA; gate open circuit	-	0.5	0.8	V
		V_D = $V_{DRM(max)}$; I_T = 10 mA; T_j = 125 ˚C; gate open circuit	0.2	0.3	-	V
I_D, I_R	Off-state leakage current	V_D = $V_{DRM(max)}$; V_R = $V_{RRM(max)}$; T_j = 125 ˚C; R_{GK} = 1 kΩ	-	0.05	0.1	mA

DYNAMIC CHARACTERISTICS

T_j = 25 ˚C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
dV_D/dt	Critical rate of rise of off-state voltage	V_{DM} =67% $V_{DRM(max)}$; T_j = 125 ˚C; exponential waveform; R_{GK} = 1k Ω	-	25	-	V/µs
t_{gt}	Gate controlled turn-on time	I_{TM} = 2 A; V_D = $V_{DRM(max)}$; I_G = 10 mA; dI_G/dt = 0.1 A/µs	-	2	-	µs
t_q	Circuit commutated turn-off time	V_D = 67% $V_{DRM(max)}$; T_j = 125 ˚C; I_{TM} = 1.6 A; V_R = 35 V; dI_{TM}/dt = 30 A/µs; dV_D/dt = 2 V/µs; R_{GK} = 1 kΩ	-	100	-	µs

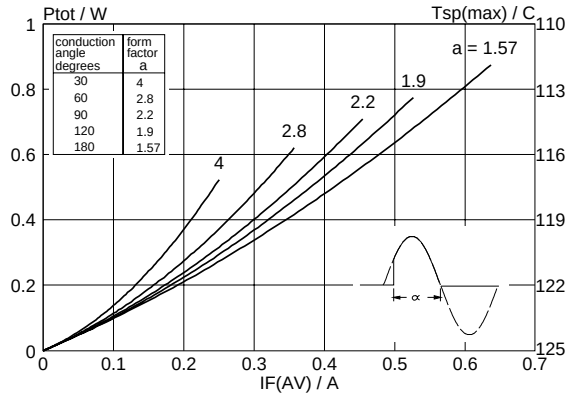


Fig.1. Maximum on-state dissipation, P_{tot}, versus average on-state current, $I_{T(AV)}$, where a = form factor = $I_{T(RMS)}$/ $I_{T(AV)}$.

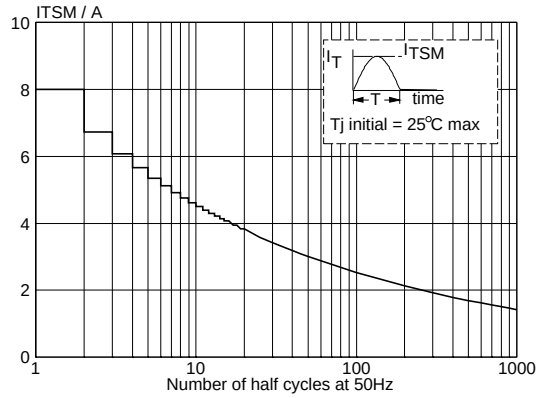


Fig.4. Maximum permissible non-repetitive peak on-state current I_{TSM}, versus number of cycles, for sinusoidal currents, f = 50 Hz.

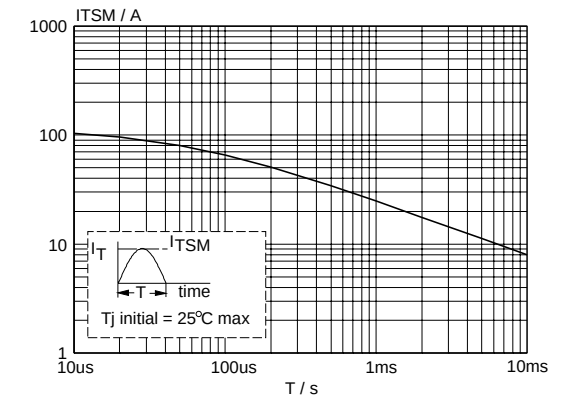


Fig.2. Maximum permissible non-repetitive peak on-state current I_{TSM}, versus pulse width t_p, for sinusoidal currents, $t_p \leq 10ms$.

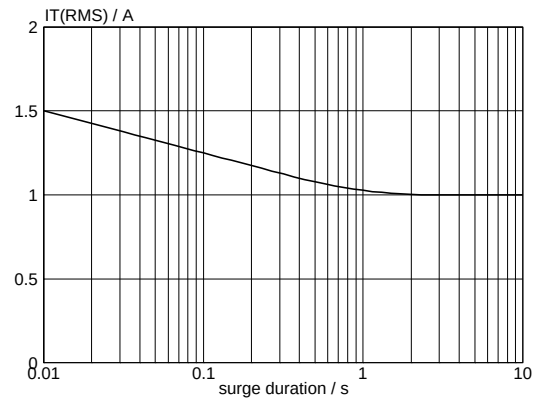


Fig.5. Maximum permissible repetitive rms on-state current $I_{T(RMS)}$, versus surge duration, for sinusoidal currents, f = 50 Hz; $T_{sp} \leq 112˚C$.

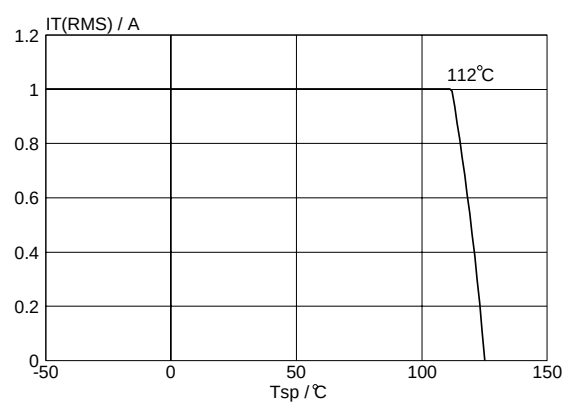


Fig.3. Maximum permissible rms current $I_{T(RMS)}$, versus solder point temperature T_{sp}.

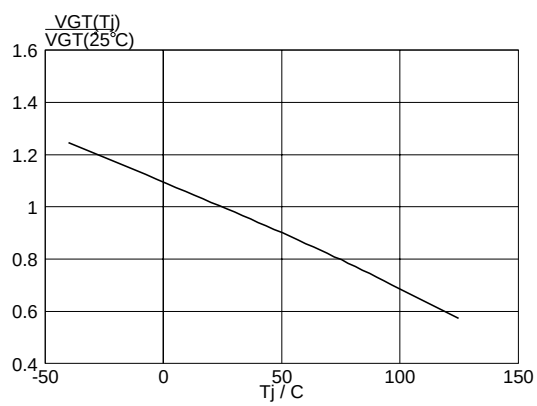


Fig.6. Normalised gate trigger voltage $V_{GT}(T_j)$/ $V_{GT}(25˚C)$, versus junction temperature T_j.

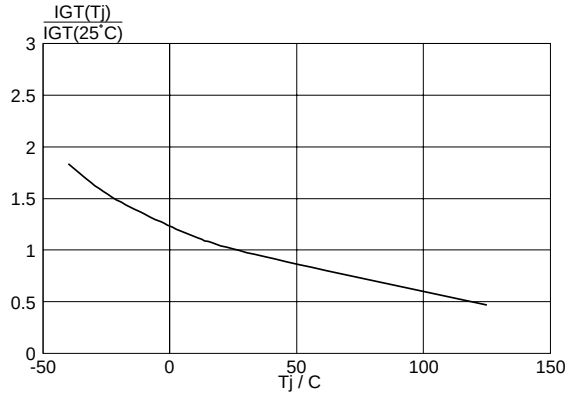


Fig.7. Normalised gate trigger current $I_{GT}(T_j)/ I_{GT}(25˚C)$, versus junction temperature T_j.

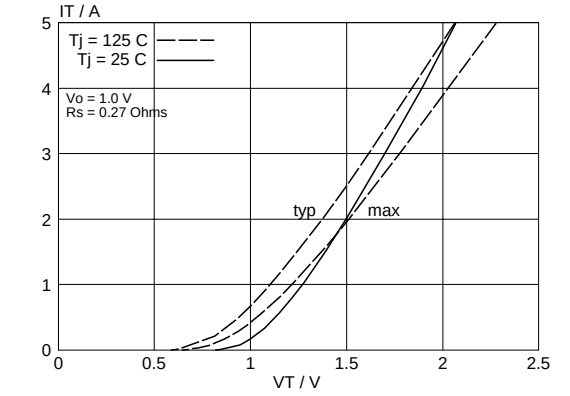


Fig.10. Typical and maximum on-state characteristic.

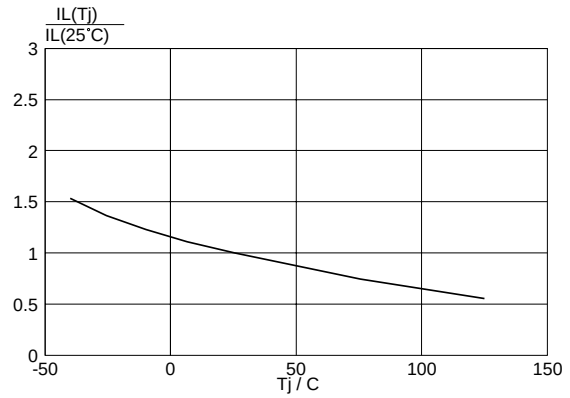


Fig.8. Normalised latching current $I_L(T_j)/ I_L(25˚C)$, versus junction temperature T_j, R_{GK} = 1 kΩ.

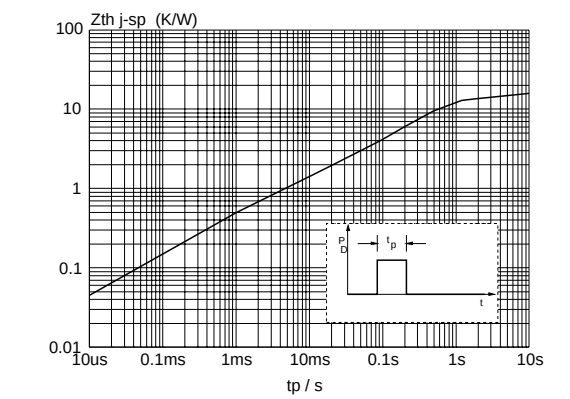


Fig.11. Transient thermal impedance $Z_{th\ j\text{-}sp}$, versus pulse width t_p.

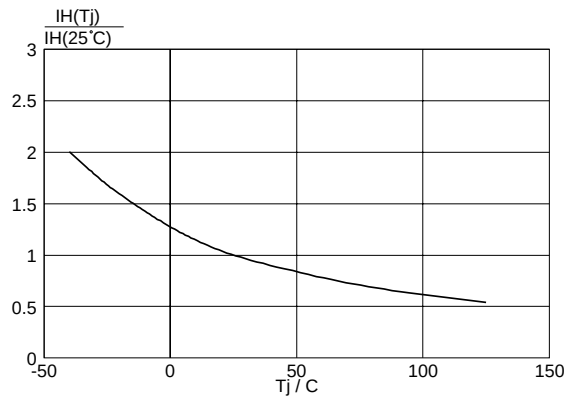


Fig.9. Normalised holding current $I_H(T_j)/ I_H(25˚C)$, versus junction temperature T_j, R_{GK} = 1 kΩ.

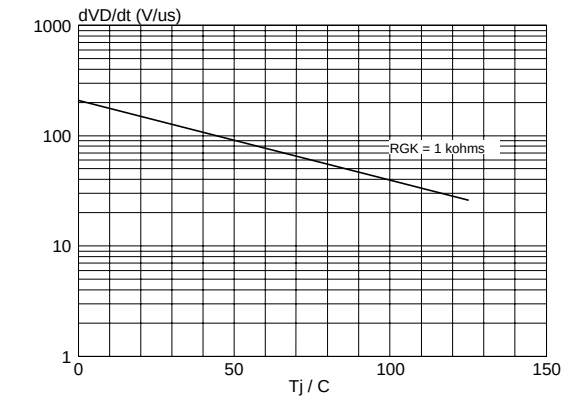


Fig.12. Typical, critical rate of rise of off-state voltage, dV_D/dt versus junction temperature T_j.

MOUNTING INSTRUCTIONS

Dimensions in mm.

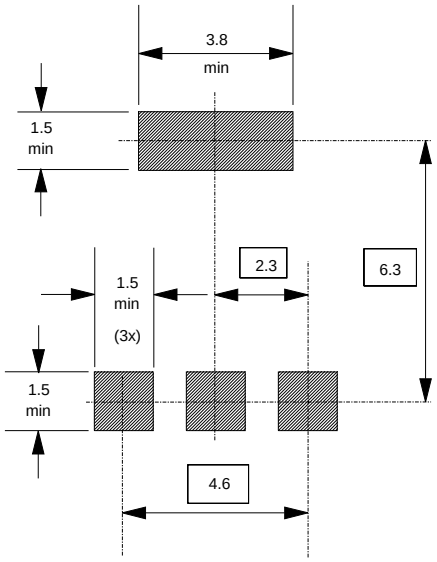


Fig.13. soldering pattern for surface mounting SOT223.

MECHANICAL DATA

Dimensions in mm

Net Mass: 0.11 g

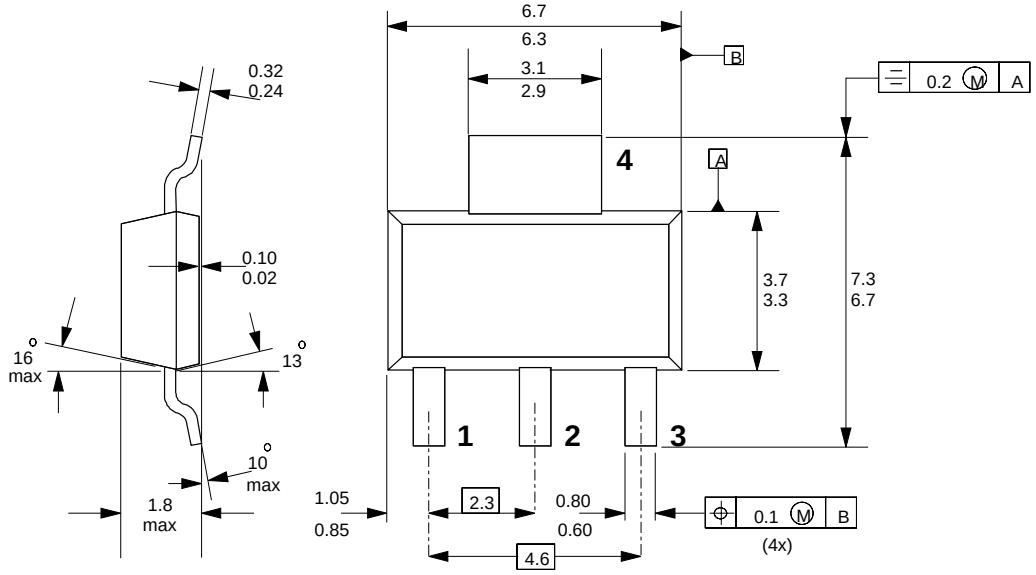


Fig.14. SOT223 surface mounting package.

Notes

1. For further information, refer to Philips publication SC18 " SMD Footprint Design and Soldering Guidelines". Order code: 9397 750 00505.
2. Epoxy meets UL94 V0 at 1/8".

DEFINITIONS

DATA SHEET STATUS		
DATA SHEET STATUS[2]	**PRODUCT STATUS**[3]	**DEFINITIONS**
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice
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Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A
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Application information		
Where application information is given, it is advisory and does not form part of the specification.		

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